



Super Fast Recovery Rectifier Diode

MUR3060PT





TO-3P Plastic Package RoHS compliant

TO-3P

GENERAL DESCRIPTION:

Mainly used in switching power supply, PWM pulse width modulator, inverter as a freewheeling and other electronic circuits, high-frequency rectifier diode, diode or damping diode use

FEATURES

- 1. Super fast switching for high efficiency.
- 2. Low reverse leakage.
- 3. High forward surge current capability.
- 4. RoHs Product.

APPLICATIONS:

MUR3060PT Device optimized for ultra-low forward voltage drop to maximize efficiency in Power Supply applications.

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	VALUE	UNIT
Maximal Inverted Repetitive Peak Voltage	V _{RRM}	600	V
*Average Rectified Forward Current (Rated VR-20Khz Square Wave) - 50% duty cycle	I _{FAV}	30	А
Reverse Recovery Time(IF=0.5A IR=1.0A IREC=0.25A)	T _{RR}	≤50	nS
Forward Peak Surge Current(Rated Load 8.3 Half Sine Wave According to JEDEC Method)	I _{FSM}	130x2	А
Operating Junction Temperature	TJ	150	°C
Storage Temperature	T _{STG}	-55 to +125	°C
Typical Thermal Resistance(per leg)	R _{eJC}	0.5	°C/W





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ELECTRICAL CHARACTERISTICS at (Ta = 25 °C Unless otherwise specified)

Parameter		SYMBOL	Test Condition	Value			Unit
		OTMEOL	rest condition	Min	Тур.	Max	onic
Reverse breakdown voltag	le,	V _B	I _R =100uA	600			V
Peak Reverse Current,	TJ =25°C	I _R	V _R =600V			0.01	mA
	TJ =125°C		V _R =600V			0.20	mA
	TJ =25°C		I _F =15A		1.47	1.8	V
Forward voltage,	TJ =125°C	V _F	(I _{FAV} =15A×2)	1	-	1.45	V



Recommended Reflow Solder Profiles

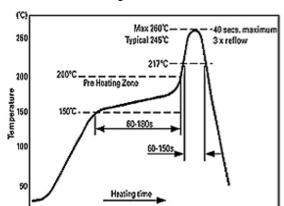
The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

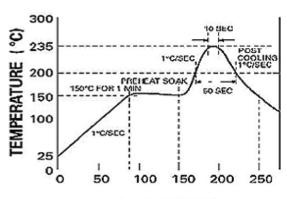
Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.

Figure 1

Figure 2





TIME (SEC)

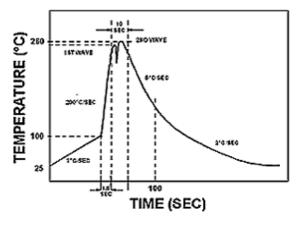
Profile Feature	Sn-Pb System	Pb-Free System		
Average Ramp-Up Rate	~3°C/second	~3°C/second		
Preheat				
– Temperature Range	150-170°C	150-200°C		
– Time	60-180 seconds	60-180 seconds		
Time maintained above:				
– Temperature	200°C	217°C		
– Time	30-50 seconds	60-150 seconds		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	40 seconds		
Ramp-Down Rate	3°C/second max.	6°C/second max.		



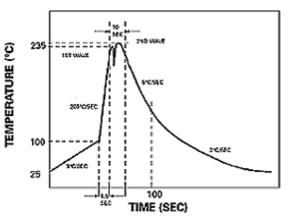


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used



The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder

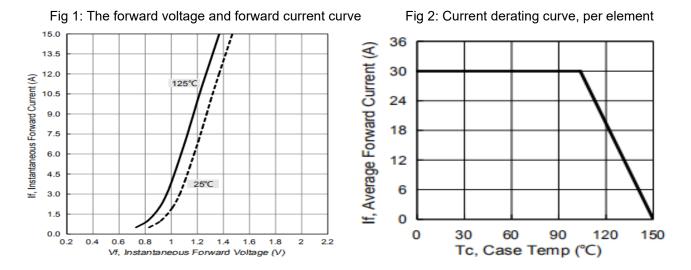


Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System	
Average Ramp-Up Rate	~200°C/second	~200°C/second	
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec	
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp	
Peak Temperature	235°C	260°C max.	
Time within +0 -5°C of actual Peak	10 seconds	10 seconds	
Ramp-Down Rate	5°C/second max.	5°C/second max.	





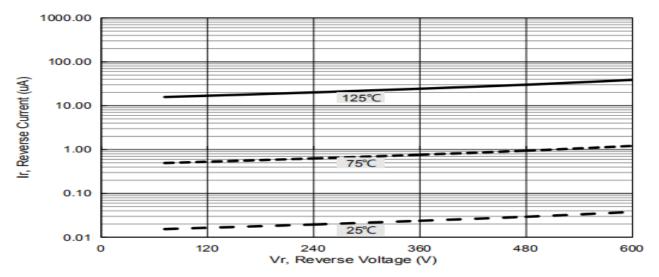


SYSTEMCER

DNV

SUL

Fig 3: The reverse leak current and the reverse voltage (single-device) curve



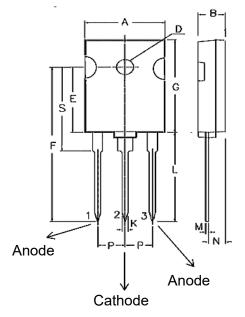
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Package Details

TO-3P PACKAGE OUTLINE AND DIMENSIONS



DIM	MIN.	MAX.
A	15.20	15.80
В	4.90	5.10
D	3.90	4.10
E	14.20	14.80
F	28.20	30.50
G	19.50	19.80
K	1.00	1.30
L	14.10	17.50
М	0.40	0.60
N	2.50	2.75
Р	5.21	5.72
S	18.25	19.25

ALL DIMENSIONS IN MM

PIN CONFIGURATION

- 1. Anode
- 2. Cathode
- 3. Anode

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Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- $\cdot\,$ Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start. For this, the following JEDEC table may be referred:

JEDEC MSL Level			
Level	Time	Condition	
1	Unlimited	≤30 °C / 85%	
2	1 Year	≤30 °C / 60%	
2a	4 Weeks	≤30 °C / 60%	
3	168 Hours	≤30 °C / 60%	
4	72 Hours	≤30 °C / 60%	
5	48 Hours	≤30 °C / 60%	
5a	24 Hours	≤30 °C / 60%	
6	Time on Label(TOL)	≤30 °C / 60%	





Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are R Ohs compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the Coil's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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